

ABSTRACT OF THE DISCLOSURE

METHOD FOR PRODUCING BUMP-FORMED PLATE-LIKE MEMBER, 5 BUMP-FORMED PLATE-LIKE MEMBER, METHOD FOR PRODUCING ELECTRONIC COMPONENT, AND ELECTRONIC COMPONENT

The present invention provides a method for producing a bump-formed
plate-like member that allows simple and efficient production of an electronic
10 component having both of a via electrode(s) and a plate-like member. The method
for producing a bump-formed plate-like member according to the present invention
is a method for producing a member for an electronic component obtained by
encapsulating at least one chip in a resin. The member is a bump-formed plate-like
member 10 including a plate-like member 11 having a surface on which at least one
15 bump 12 is formed. The method includes molding the plate-like member 11 and
the at least one bump 12 at the same time by molding using a molding die.

Fig. 5

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